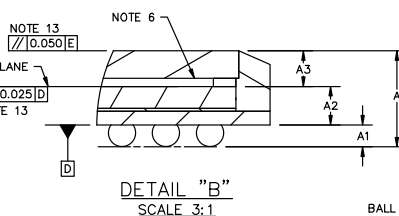
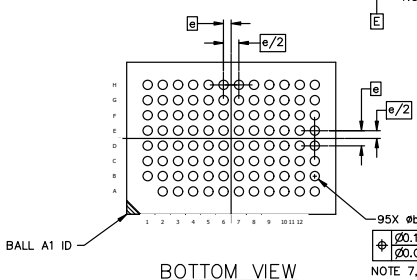
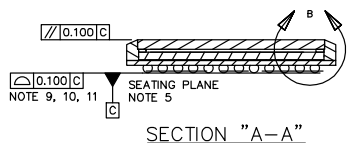
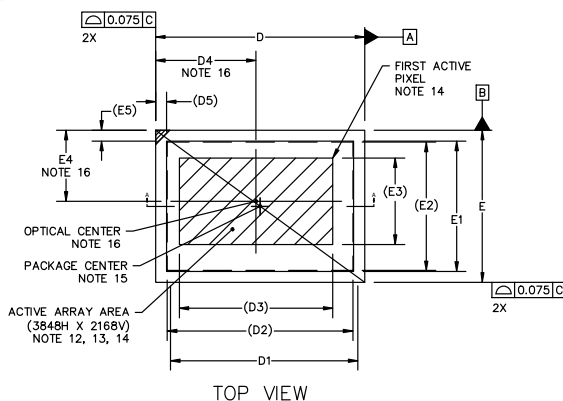
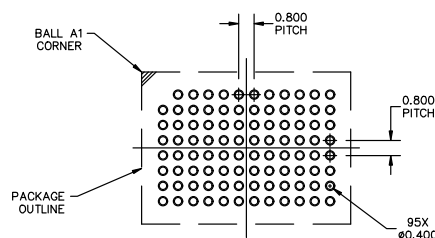


IBGA95 11.00x8.00x1.35, 0.80P
CASE 503CV
ISSUE O

DATE 07 OCT 2024



MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	1.900
A1	0.350	0.400	0.450
A2	0.650	0.700	0.750
A3	0.600	0.650	0.700
b	0.480	0.530	0.580
D	10.925	11.000	11.075
D1	9.750	9.850	9.950
D2	9.760 REF		
D3	8.081 REF		
D4	5.211	5.286	5.361
D5	0.575 REF		
E	7.925	8.000	8.075
E1	6.750	6.850	6.950
E2	6.760 REF		
E3	4.553 REF		
E4	3.660	3.735	3.810
E5	0.575 REF		
e	0.800 BSC		



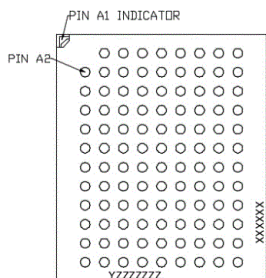
RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. CONTROLLING DIMENSION: MILLIMETERS [mm].
2. ENCAPSULANT: EPOXY.
3. SUBSTRATE MATERIAL: EPOXY LAMINATE 0.250 THICKNESS.
4. GLASS 0.500 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<1% 420-850nm (EACH SIDE).
5. IMAGING SENSOR DIE: 0.400 THICKNESS.
6. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.150 THICKNESS.
7. SOLDER BALL MATERIAL: SAC305 (96.5% Sn, 3% Ag, 0.5% Cu). RAW BALL DIAMETER: 0.500mm.
8. SOLDER BALL PAD: 0.400 SMD.
9. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
10. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
11. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
12. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±0.7°.
13. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
14. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
15. PACKAGE CENTER (X, Y) = (0.000, 0.000); DIE CENTER (X, Y) = (0.000, 0.000).
16. OPTICAL CENTER (X, Y) = (-0.214, 0.265).
17. DIMENSIONING AND TOLERANCING AS PER ASMEY14.5M, 2018.

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON65518H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	IBGA95 11.00x8.00x1.35, 0.80P	PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.